

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	7	29/846.ccls. and ((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:31
L4	20	(29/825,829-832).ccls. and ((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:32
L5	24	(257/686,778).ccls. and ((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB) and flexible	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:40
L6	24	(257/686,778).ccls. and ((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB) and flexible	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:40
L7	1	(264/263,272.15).ccls. and ((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB) and flexible	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:41
L8	5	(361/749,796,803).ccls. and ((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB) and flexible	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:42
L9	193	((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB) and flexible	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:42
L12	2	((semiconductor or chip or component or IC) near (structure or module)) with mold\$3 and (board or motherboard or PCB) and flexible and (requir\$3 or only or during) and (eliminat\$3 or remov\$3 or discard\$3) with (alter\$3 or modif\$4 or affect\$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/07/13 15:46